

H48-2K

Thermal Pad



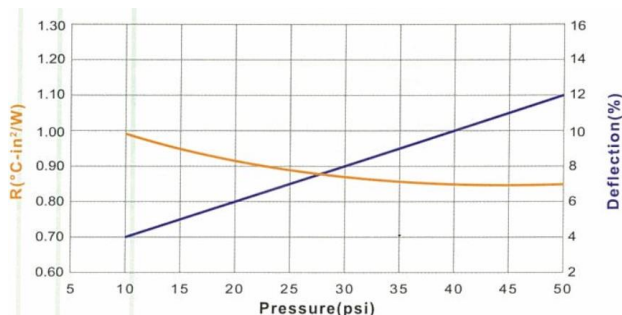
Features

- Very low thickness available
- Low contact thermal impedance
- Low-oil bleed
- High dielectric breakdown voltage

Applications

- Suitable for light electronics
- Electronic components: IC, CPU, MOS, LED,
- Mother Board, Power Supply, Heat Sink, LCD-TV,
- Notebook, PC, Telecom Device, Wireless Hub,
- DDR II Module, DVD Applications, Hand-set Applications etc.

Thermal Resistance VS. Pressure VS. Deflection

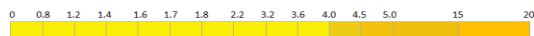


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.99	4
30	0.88	8
50	0.85	12

Properties ◆ REACH Compliant ◆ RoHS Compliant ◆ UL Compliant

Thermal Conductivity: 2.2W/m.K

Hardness: 85 (Shore A)

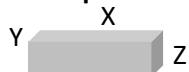


Testing sample thickness: 0.3mm

In "Thermal resistance VS. Pressure VS. Deflection" chart, H48-2K provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. H48-2K provides good compliance and softness.

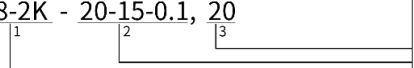
Properties	H48-2K	Unit	Tolerance	Test Method
Thermal Conductivity	2.2	W / mK	±0.2	ASTM 5470
Thickness	0.1/0.2/0.3	mm	-	ASTM D374
Color	Dark Red	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	1.2/2.5/3.5	KV	±0.1/±0.2/±0.3	ASTM D149
Weight Loss	<0.5	%	-	ASTM E595
Density	2.4	g / cm ³	±0.2	ASTM D792
Working Temperature	-45~+200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-m	-	ASTM D257
Elongation	50	%	-	ASTM D412
Tensile Strength	200	N / mm ²	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness	85	Shore A	±5	ASTM D2240

Need Samples?



Pre-cut for different shapes

H48-2K - 20-15-0.1, 20



1. Choose the P/N
2. Fill into size: X, Y, Z
3. Fill the quantity you need

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

Version4 20170701